

TECHNICAL DATA SHEET

Levon[™] HP6 Precision Vacuum Hotplate

Ø170 mm vacuum heating plate · wafers up to 6 inches · RT to 250°C · $\pm 0.2^{\circ}\text{C}$ precision after stabilization · $\leq 1\%$ uniformity



Levon[™] HP6 Precision Vacuum Hotplate — Representative Configuration

The Levon[™] HP6 Precision Vacuum Hotplate is a compact vacuum hot plate with a Ø170 mm hard-anodized aluminum heating plate, a manually activated vacuum chuck and a thermal-radiation-sealed lid. Image shown for reference; final configuration is confirmed in the quotation.

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SECTION I

Product Overview

Levon™ HP6 Precision Vacuum Hotplate is a vacuum hot plate with a Ø170 mm circular heating plate for wafers up to 6 inches, a temperature control range of RT to 250°C, 0.1°C temperature resolution, ±0.2°C temperature control precision (after the temperature is stable) and ≤1% temperature uniformity.

The HP6 has a manually activated vacuum substrate chuck with a close-contact resist baking mode, a digital temperature controller with an optional linear control function, a thermal-radiation-sealed lid over a hard-anodized aluminum heating plate and an independent control circuit for the heating output. The full anodized aluminum body has a recessed heating element design with compact dimensions (370 × 270 × 126 mm, W × D × H) for glovebox integration. Vacuum is connected at the rear-panel outlet (6 mm outer diameter); the vacuum input requirement is 0.04–0.09 MPa.

SECTION II

Core Advantages

- **Vacuum substrate chuck** Manually activated vacuum substrate chuck with a close-contact resist baking mode.
- **Digital temperature controller** Digital temperature controller with an optional linear control function; ±0.2°C control precision after the temperature is stable.
- **Thermal-radiation-sealed lid** Thermal-radiation-sealed lid over a hard-anodized aluminum heating plate.
- **Independent heating circuit** Independent control circuit for the heating output.
- **Glovebox integration** Recessed heating element design with compact dimensions for glovebox integration.
- **Anodized aluminum body** Full anodized aluminum body structure; 370 × 270 × 126 mm (W × D × H).

SECTION III

Specifications

Technical data — HP6

Specifications	
Parameter	Specification
Brand	Levon™ by ACS Material
Product Name	Levon™ HP6 Precision Vacuum Hotplate
Model	HP6
SKU #	LVHP0600
Product type	Vacuum hotplate
Heating plate	Ø170 mm circular, hard-anodized aluminum
Applicable substrate size	Wafers up to 6 inches
Temperature control range	RT to 250°C
Temperature resolution	0.1°C
Temperature control precision	±0.2°C (after the temperature is stable)
Temperature uniformity	≤1%
Temperature controller	Digital temperature controller with optional linear control function
Vacuum chuck	Manually activated vacuum substrate chuck; close-contact resist baking mode
Vacuum interface	Rear-panel outlet, 6 mm outer diameter
Vacuum input requirement	0.04–0.09 MPa
Lid	Thermal-radiation-sealed lid
Body	Full anodized aluminum body; recessed heating element design for glovebox integration
Heating output	Independent circuit control
Power input	220 V, 1,000 W
Dimensions [W × D × H]	370 × 270 × 126 mm
Packing	Carton packaging
Warranty	1-year product warranty

Scope of delivery

- **Standard configuration:** one HP6 main unit, carton packaging.
- **Vacuum supply** — provided by the user: 0.04–0.09 MPa at the rear-panel outlet (6 mm outer diameter).

SECTION IV

Applications

For close-contact resist baking of wafers up to 6 inches on a vacuum-held Ø170 mm plate from RT to 250°C, including glovebox setups. The HP6 is designed for compact semiconductor research.

Product value: vacuum-held close-contact baking of wafers up to 6 inches to 250°C, ±0.2°C control precision after stabilization and a compact, glovebox-ready body.

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